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DOCKET NO.: 01-C-055  
CLIENT NO.: STMI01-01055  
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PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: : Harry Michael Siegel et al.  
Application No. : 10/062,595  
Filed : January 31, 2002  
For : SYSTEM AND METHOD FOR ALIGNING AN  
INTEGRATED CIRCUIT DIE ON AN INTEGRATED  
CIRCUIT SUBSTRATE  
Group No. : 3725  
Examiner : David B. Jones

**MAIL STOP ISSUE FEE**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

**CERTIFICATE OF MAILING BY FIRST CLASS MAIL**

Sir:

The undersigned hereby certifies that the following documents:


1. Amendment Under 37 C.F.R. § 1.312;
2. One (1) sheet of Replacement drawing;
3. Redline copy of drawing; and
4. A postcard receipt

relating to the above application, were deposited as "First Class Mail" with the United States Postal Service, addressed to Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on July 18, 2005.

Date: July 18, 2005

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